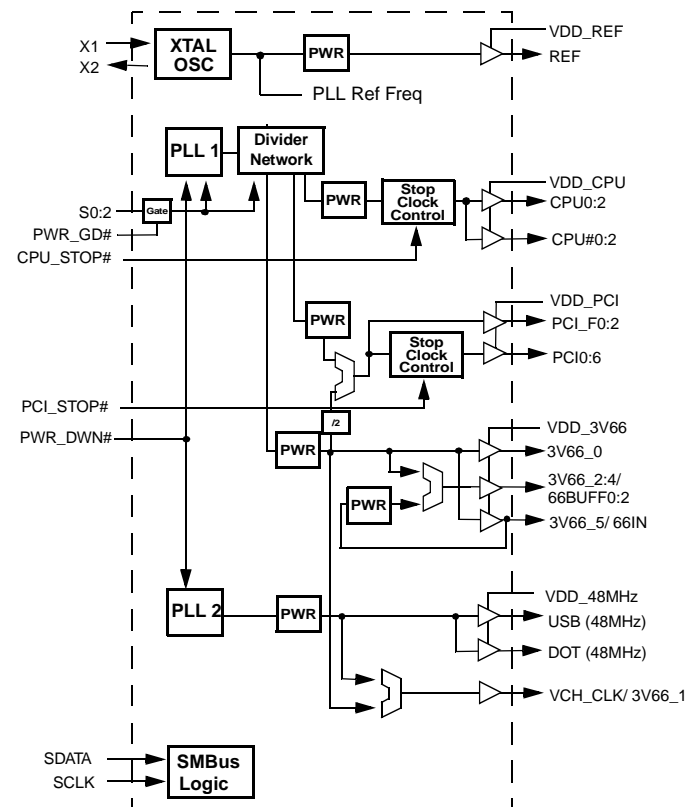


**CYPRESS****PRELIMINARY****W320-03**

# 200-MHz Spread Spectrum Clock Synthesizer/Driver with Differential CPU Outputs

Features	Benefits
<ul style="list-style-type: none"><li>Compliant to Intel® CK-Titan Clock Synthesizer/Driver Specifications</li></ul>	Supports next generation Pentium® processors using differential clock drivers
<ul style="list-style-type: none"><li>Multiple output clocks at different frequencies<ul style="list-style-type: none"><li>Three pairs of differential CPU outputs, up to 200 MHz</li><li>Ten synchronous PCI clocks, three free-running</li><li>Six 3V66 clocks</li><li>Two 48-MHz clocks</li><li>One reference clock at 14.318 MHz</li><li>One VCH clock</li></ul></li></ul>	Motherboard clock generator <ul style="list-style-type: none"><li>Support Multiple CPUs and a chipset</li><li>Support for PCI slots and chipset</li><li>Supports AGP, DRCG reference and Hub Link</li><li>Supports USB host controller and graphic controller</li><li>Supports ISA slots and I/O chip</li></ul>
<ul style="list-style-type: none"><li>Spread Spectrum clocking (down spread)</li></ul>	Enables reduction of EMI and overall system cost
<ul style="list-style-type: none"><li>Power-down features (PCI_STOP#, CPU_STOP# PWR_DWN#)</li></ul>	Enables ACPI compliant designs
<ul style="list-style-type: none"><li>Three Select inputs (Mode select &amp; IC Frequency Select)</li></ul>	Supports up to four CPU clock frequencies
<ul style="list-style-type: none"><li>OE and Test Mode support</li></ul>	Enables ATE and “bed of nails” testing
<ul style="list-style-type: none"><li>56-pin SSOP package and 56-pin TSSOP package</li></ul>	Widely available, standard package enables lower cost

## Logic Block Diagram



## Pin Configurations

### SSOP & TSSOP

#### Top View

VDD_REF	1	56	REF
XTAL_IN	2	55	S1
XTAL_OUT	3	54	S0
GND_REF	4	53	CPU_STOP#
PCI_F0	5	52	CPU0
PCI_F1	6	51	CPU#0
PCI_F2	7	50	VDD_CPU
VDD_PCI	8	49	CPU1
GND_PCI	9	48	CPU#1
PCI0	10	47	GND_CPU
PCI1	11	46	VDD_CPU
PCI2	12	45	CPU2
PCI3	13	44	CPU#2
VDD_PCI	14	43	MULT0
GND_PCI	15	42	IREF
PCI4	16	41	GND_IREF
PCI5	17	40	S2
PCI6	18	39	USB
VDD_3V66	19	38	DOT
GND_3V66	20	37	VDD_48 MHz
66BUFF0/3V66_2	21	36	GND_48 MHz
66BUFF1/3V66_3	22	35	3V66_1/VCH
66BUFF2/3V66_4	23	34	PCI_STOP#
66IN/3V66_5	24	33	3V66_0
PWR_DWN#	25	32	VDD_3V66
VDD_CORE	26	31	GND_3V66
GND_CORE	27	30	SCLK
PWR_GD#	28	29	SDATA

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**Pin Summary**

Name	Pins	Description
REF	56	3.3V 14.318-MHz clock output
XTAL_IN	2	14.318-MHz crystal input
XTAL_OUT	3	14.318-MHz crystal input
CPU, CPU# [0:2]	44, 45, 48, 49, 51, 52	Differential CPU clock outputs
3V66_0	33	3.3V 66-MHz clock output
3V66_1/VCH	35	3.3V selectable through SMBus to be 66 MHz or 48 MHz
66IN/3V66_5	24	66-MHz input to buffered 66BUFF and PCI or 66-MHz clock from internal VCO
66BUFF [2:0] /3V66 [4:2]	21, 22, 23	66-MHz buffered outputs from 66Input or 66MHz clocks from internal VCO
PCI_F [0:2]	5, 6, 7,	33 MHz clocks divided down from 66Input or divided down from 3V66
PCI [0:6]	10, 11, 12, 13, 16, 17, 18	PCI clock outputs divided down from 66Input or divided down from 3V66
USB	39	Fixed 48-MHz clock output
DOT	38	Fixed 48-MHz clock output
S2	40	Special 3.3V 3 level input for Mode selection
S1, S0	54, 55	3.3V LVTTL inputs for CPU frequency selection
IREF	42	A precision resistor is attached to this pin which is connected to the internal current reference
MULT0	43	3.3V LVTTL input for selecting the current multiplier for the CPU outputs
PWR_DWN#	25	3.3V LVTTL input for Power_Down# (active LOW)
PCI_STOP#	34	3.3V LVTTL input for PCI_STOP# (active LOW)
CPU_STOP#	53	3.3V LVTTL input for CPU_STOP# (active LOW)
PWRGD#	28	3.3V LVTTL input is a level sensitive strobe used to determine when S[2:0] and MULTI0 inputs are valid and OK to be sampled (Active LOW). Once PWRGD# is sampled LOW, the status of this output will be ignored.
SDATA	29	SMBus compatible SDATA
SCLK	30	SMBus compatible Sclk
VDD_REF, VDD_PCI, VDD_3V66, VDD_48 MHz, VDD_CPU	1, 8, 14, 19, 32, 37, 46, 50	3.3V power supply for outputs
VDD_CORE	26	3.3V power supply for PLL
GND_REF, GND_PCI, GND_3V66, GND_IREF, VDD_CPU	4, 9, 15, 20, 31, 36, 41, 47	Ground for outputs
GND_CORE	27	Ground for PLL

**Function Table<sup>[1]</sup>**

S2	S1	S0	CPU (MHz)	3V66[0:1] (MHz)	66BUFF[0:2]/3V66[2:4] (MHz)	66IN/3V66_5 (MHz)	PCI_F/PCI (MHz)	REF0(MHz)	USB/DOT (MHz)	Notes:
1	0	0	66 MHz	66 MHz	66 IN	66 MHz Input	66 IN/2	14.318 MHz	48 MHz	2, 3, 4
1	0	1	100 MHz	66 MHz	66 IN	66 MHz Input	66 IN/2	14.318 MHz	48 MHz	2, 3, 4
1	1	0	200 MHz	66 MHz	66 IN	66 MHz Input	66 IN/2	14.318 MHz	48 MHz	2, 3, 4
1	1	1	133 MHz	66 MHz	66 IN	66 MHz Input	66 IN/2	14.318 MHz	48 MHz	2, 3, 4
0	0	0	66 MHz	66 MHz	66 MHz	66 MHz	33 MHz	14.318 MHz	48 MHz	2, 3, 4
0	0	1	100 MHz	66 MHz	66 MHz	66 MHz	33 MHz	14.318 MHz	48 MHz	2, 3, 4
0	1	0	200 MHz	66 MHz	66 MHz	66 MHz	33 MHz	14.318 MHz	48 MHz	2, 3, 4
0	1	1	133 MHz	66 MHz	66 MHz	66 MHz	33 MHz	14.318 MHz	48 MHz	2, 3, 4
Mid	0	0	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	1, 5
Mid	0	1	TCLK/2	TCLK/4	TCLK/4	TCLK/4	TCLK/8	TCLK	TCLK/2	7, 8, 5
Mid	1	0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	--
Mid	1	1	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	--

**Swing Select Functions**

Mult0	Board Target Trace/Term Z	Reference R, IREF = $V_{DD}/(3 \cdot R_r)$	Output Current	$V_{OH} @ Z$
0	60Ω	$R_r = 221\%$ , IREF = 5.00 mA	$I_{OH} = 4 \cdot IREF$	1.0V @ 50
1	50Ω	$R_r = 475\%$ , IREF = 2.32 mA	$I_{OH} = 6 \cdot IREF$	0.7V @ 50

**Clock Driver Impedances**

Buffer Name	$V_{DD}$ Range	Buffer Type	Impedance		
			Minimum Ω	Typical Ω	Maximum Ω
CPU, CPU#		Type X1		50	
REF	3.135–3.465	Type 3	20	40	60
PCI, 3V66, 66BUFF	3.135–3.465	Type 5	12	30	55
USB	3.135–3.465	Type 3A	12	30	55
DOT	3.135–3.465	Type 3B	12	30	55

**Clock Enable Configuration**

PWR_DWN#	CPU_STOP#	PCI_STOP#	CPU	CPU#	3V66	66BUFF	PCI_F	PCI	USB/DOT	VCOS/OSC
0	X	X	IREF*2	FLOAT	LOW	LOW	LOW	LOW	LOW	OFF
1	0	0	IREF*2	FLOAT	ON	ON	ON	OFF	ON	ON
1	0	1	IREF*2	FLOAT	ON	ON	ON	ON	ON	ON
1	1	0	ON	ON	ON	ON	ON	OFF	ON	ON
1	1	1	ON	ON	ON	ON	ON	ON	ON	ON

**Note:**

1. TCLK is a test clock driven in on the XTALIN input in test mode.
2. "Normal" mode of operation
3. Range of reference frequency allowed is min. = 14.316 nominal = 14.31818 MHz, max = 14.32 MHz.
4. Frequency accuracy of 48 MHz must be +167PPM to match USB default.
5. Mid is defined a Voltage level between 1.0V and 1.8V for 3 level input functionality. Low is below 0.8V. High is above 2.0V.
6. TCLK is a test clock over driven on the XTAL\_IN input during test mode.
7. Required for DC output impedance verification.
8. These modes are to use the SAME internal dividers as the CPU = 200 MHz mode. The only change is to slow down the internal VCO to allow under clock margining.

## Serial Data Interface (SMBus)

To enhance the flexibility and function of the clock synthesizer, a two signal SMBus interface is provided according to SMBus specification. Through the Serial Data Interface, various device functions such as individual clock output buffers, etc can be individually enabled or disabled. W320-03 support both block read and block write operations.

The registers associated with the Serial Data Interface initialize to their default setting upon power-up, and therefore use of this interface is optional. Clock device register changes are normally made upon system initialization, if any are required. The interface can also be used during system operation for power management functions.

### Data Protocol

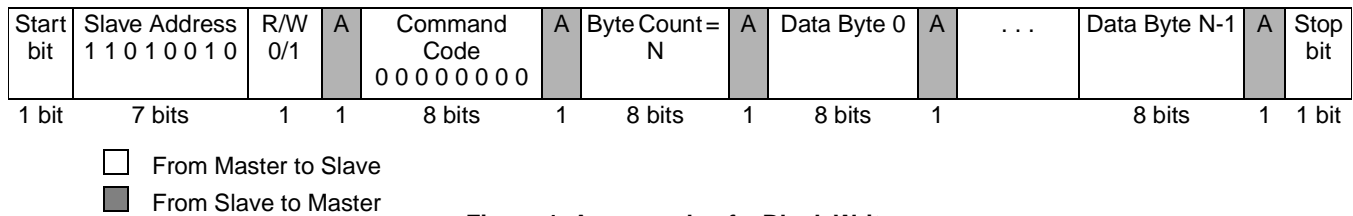
The clock driver serial protocol accepts only block writes from the controller. The bytes must be accessed in sequential order from lowest to highest byte, (most significant bit first) with the

ability to stop after any complete byte has been transferred. Indexed bytes are not allowed.

A block write begins with a slave address and a WRITE condition. The R/W bit is used by the SMBus controller as a data direction bit. A zero indicates a WRITE condition to the clock device. The slave receiver address is 11010010 (D2h).

A command code of 0000 0000 (00h) and the byte count bytes are required for any transfer. After the command code, the core logic issues a byte count which describes number of additional bytes required for the transfer, not including the command code and byte count bytes. For example, if the host has 20 data bytes to send, the first byte would be the number 20 (14h), followed by the 20 bytes of data. The byte count byte is required to be a minimum of 1 byte and a maximum of 32 bytes. It may not be 0. *Figure 1* shows an example of a block write.

A transfer is considered valid after the acknowledge bit corresponding to the byte count is read by the controller.



**Figure 1. An example of a Block Write**

## Data Byte Configuration Map

**Data Byte 0: Control Register (0 = Enable, 1 = Disable)**

Bit	Affected Pin#	Name	Description	Type	Power On Default
Bit 7	5, 6, 7, 10, 11, 12, 13, 16, 17, 18, 33, 35	PCI [0:6] CPU[2:0] 3V66[1:0]	<b>Spread Spectrum Enable</b> 0 = Spread Off, 1 = Spread On	R/W	0
Bit 6	--	TBD	TBD	R	0
Bit 5	35	3V66_1/VCH	<b>VCH Select 66 MHz/48 MHz</b> 0 = 66 MHz, 1 = 48 Mhz	R/W	0
Bit 4	44, 45, 48, 49, 51, 52	CPU [2:0] CPU# [2:0]	<b>CPU_STOP#</b> Reflects the current value of the external CPU_STOP# pin	R	N/A
Bit 3	10, 11, 12, 13, 16, 17, 18	PCI [6:0]	<b>PCI_STOP#</b> (Does not affect PCI_F [2:0] pins)	R/W	N/A
Bit 2	--	--	<b>S2</b> Reflects the value of the S2 pin sampled on Power-up	R	N/A
Bit 1	--	--	<b>S1</b> Reflects the value of the S1 pin sampled on Power-up	R	N/A
Bit 0	--	--	<b>S0</b> Reflects the value of the S1 pin sampled on Power-up	R	N/A

**Data Byte 1**

Bit	Pin#	Name	Description	Type	Power On Default
Bit 7	--	N/A	CPU Mult0 Value	R	N/A
Bit 6	--	N/A	TBD	R	0
Bit 5	44, 45	CPU2 CPU2#	Allow Control of CPU2 with assertion of CPU_STOP# 0 = Not free running; 1 = Free running	R/W	0
Bit 4	48, 49	CPU1 CPU1#	Allow Control of CPU1 with assertion of CPU_STOP# 0 = Not free running; 1 = Free running	R/W	0
Bit 3	51, 52	CPU0 CPU0#	Allow Control of CPU0 with assertion of CPU_STOP# 0 = Not free running; 1 = Free running	R/W	0
Bit 2	44, 45	CPU2 CPU2#	CPU2 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 1	48, 49	CPU1 CPU1#	CPU1 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 0	51, 52	CPU0 CPU0#	CPU0 Output Enable 1 = Enabled; 0 = Disabled	R/W	1

**Data Byte 2**

Bit	Pin#	Name	Pin Description	Type	Power On Default
Bit 7	--	N/A	N/A	R	0
Bit 6	18	PCI6	PCI6 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 5	17	PCI5	PCI5 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 4	16	PCI4	PCI4 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 3	13	PCI3	PCI3 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 2	12	PCI2	PCI2 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 1	11	PCI1	PCI1 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 0	10	PCI0	PCI0 Output Enable 1 = Enabled; 0 = Disabled	R/W	1

**Data Byte 3**

Bit	Pin#	Name	Pin Description	Type	Power On Default
Bit 7	38	DOT	DOT 48 MHz Output Enable	R/W	1
Bit 6	39	USB	USB 48 MHz Output Enable	R/W	1
Bit 5	7	PCI_F2	Allow control of PCI_F2 with assertion of PCI_STOP# 0 = Free running; 1 = Stopped with PCI_STOP#	R/W	0
Bit 4	6	PCI_F1	Allow control of PCI_F1 with assertion of PCI_STOP# 0 = Free running; 1 = Stopped with PCI_STOP#	R/W	0
Bit 3	5	PCI_F0	Allow control of PCI_F0 with assertion of PCI_STOP# 0 = Free running; 1 = Stopped with PCI_STOP#	R/W	0
Bit 2	7	PCI_F2	PCI_F2 Output Enable	R/W	1

**Data Byte 3 (continued)**

Bit	Pin#	Name	Pin Description	Type	Power On Default
Bit 1	6	PCI_F1	PCI_F1 Output Enable	R/W	1
Bit 0	5	PCI_F0	PCI_F0 Output Enable	R/W	1

**Data Byte 4**

Bit	Pin#	Name	Pin Description	Type	Power On Default
Bit 7	--	TBD	N/A	R	0
Bit 6	--	TBD	N/A	R	0
Bit 5	33	3V66_0	3V66_0 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 4	35	3V66_1/VCH	3V66_1/VCH Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 3	24	66IN/3V66_5	3V66_5 Output Enable 1 = Enable; 0 = Disable  NOTE: THIS BIT SHOULD BE USED WHEN PIN 24 IS CONFIGURED AS 3V66_5 OUTPUT. DO NOT CLEAR THIS BIT WHEN PIN 24 IS CONFIGURED AS 66IN INPUT.	R/W	1
Bit 2	23	66BUFF2	66 MHz Buffered 2 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 1	22	66BUFF1	66 MHz Buffered 1 Output Enable 1 = Enabled; 0 = Disabled	R/W	1
Bit 0	21	66BUFF0	66 MHz Buffered 0 Output Enable 1 = Enabled; 0 = Disabled	R/W	1

**Data Byte 5**

Bit	Pin#	Name	Pin Description	Type	Power On Default
Bit 7		N/A	N/A	R	0
Bit 6		N/A	N/A	R	0
Bit 5		66BUFF [2:0]	Tpd 66IN to 66BUFF propagation delay control	R/W	0
Bit 4		66BUFF [2:0]		R/W	0
Bit 3		DOT	DOT edge rate control	R/W	0
Bit 2		DOT		R/W	0
Bit 1		USB	USB edge rate control	R/W	0
Bit 0		USB		R/W	0

**Byte 6: Vendor ID**

Bit	Description	Type	Power On Default
Bit 7	Revision Code Bit 3	R	0
Bit 6	Revision Code Bit 2	R	0
Bit 5	Revision Code Bit 1	R	0
Bit 4	Revision Code Bit 0	R	1
Bit 3	Vendor ID Bit 3	R	0

**Byte 6: Vendor ID** (continued)

Bit	Description	Type	Power On Default
Bit 2	Vendor ID Bit 2	R	1
Bit 1	Vendor ID Bit 1	R	0
Bit 0	Vendor ID Bit 0	R	0

**Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Supply Voltage ..... -0.5 to +7.0V

Input Voltage ..... -0.5V to  $V_{DD}+0.5$

Storage Temperature (Non-Condensing) ... -65°C to +150°C

Max. Soldering Temperature (10 sec) ..... +260°C

Junction Temperature ..... +150°C

Package Power Dissipation ..... 1W

Static Discharge Voltage

(per MIL-STD-883, Method 3015) ..... >2000V

**Operating Conditions** Over which Electrical Parameters are Guaranteed

Parameter	Description	Min.	Max.	Unit
$V_{DD\_REF}$ , $V_{DD\_PCI}$ , $V_{DD\_CORE}$ , $V_{DD\_3V66}$ , $V_{DD\_48\text{ MHz}}$ , $V_{DD\_CPU}$	3.3V Supply Voltages	3.135	3.465	V
$T_A$	Operating Temperature, Ambient	0	70	°C
$C_{in}$	Input Pin Capacitance		5	pF
$C_{XTAL}$	XTAL Pin Capacitance		22.5	pF
$C_L$	Max. Capacitive Load on USBCLK, REF PCICLK, 3V66		20 30	pF
$f_{(REF)}$	Reference Frequency, Oscillator Nominal Value	14.318	14.318	MHz

**Electrical Characteristics** Over the Operating Range

Parameter	Description	Test Conditions	Min.	Max.	Unit
$V_{IH}$	High-level Input Voltage	Except Crystal Pads. Threshold voltage for crystal pads = $V_{DD}/2$	2.0		V
$V_{IL}$	Low-level Input Voltage	Except Crystal Pads		0.8	V
$V_{OH}$	High-level Output Voltage	USB, REF, 3V66	$I_{OH} = -1\text{ mA}$	2.4	V
		PCI		2.4	V
$V_{OL}$	Low-level Output Voltage	USB, REF, 3V66	$I_{OL} = 1\text{ mA}$	0.4	V
		PCI		0.55	V
$I_{IH}$	Input High Current	$0 \leq V_{IN} \leq V_{DD}$	-5	5	mA
$I_{IL}$	Input Low Current	$0 \leq V_{IN} \leq V_{DD}$	-5	5	mA
$I_{OH}$	High-level Output Current	CPU For $I_{OH} = 6 \cdot I_{REF}$ Configuration	Type X1, $V_{OH} = 0.65\text{V}$	12.9	mA
			Type X1, $V_{OH} = 0.74\text{V}$	14.9	
		REF, DOT, USB	Type 3, $V_{OH} = 1.00\text{V}$	-29	
			Type 3, $V_{OH} = 3.135\text{V}$	-23	
		3V66, DOT, PCI	Type 5, $V_{OH} = 1.00\text{V}$	-33	
			Type 5, $V_{OH} = 3.135\text{V}$	-33	
$I_{OL}$	Low-level Output Current	REF, DOT, USB	Type 3, $V_{OL} = 1.95\text{V}$	29	mA
			Type 3, $V_{OL} = 0.4\text{V}$	27	
		3V66, PCI	Type 5, $V_{OL} = 1.95\text{ V}$	30	
			Type 5, $V_{OL} = 0.4\text{V}$	38	
$I_{OZ}$	Output Leakage Current	Three-state		10	mA
$I_{DD3}$	3.3V Power Supply Current	$V_{DD\_CORE}/V_{DD33} = 3.465\text{V}$ , $F_{CPU} = 133\text{ MHz}$		250	mA
$I_{DDPD3}$	3.3V Shutdown Current	$V_{DD\_CORE}/V_{DDQ3} = 3.465\text{V}$		20	mA

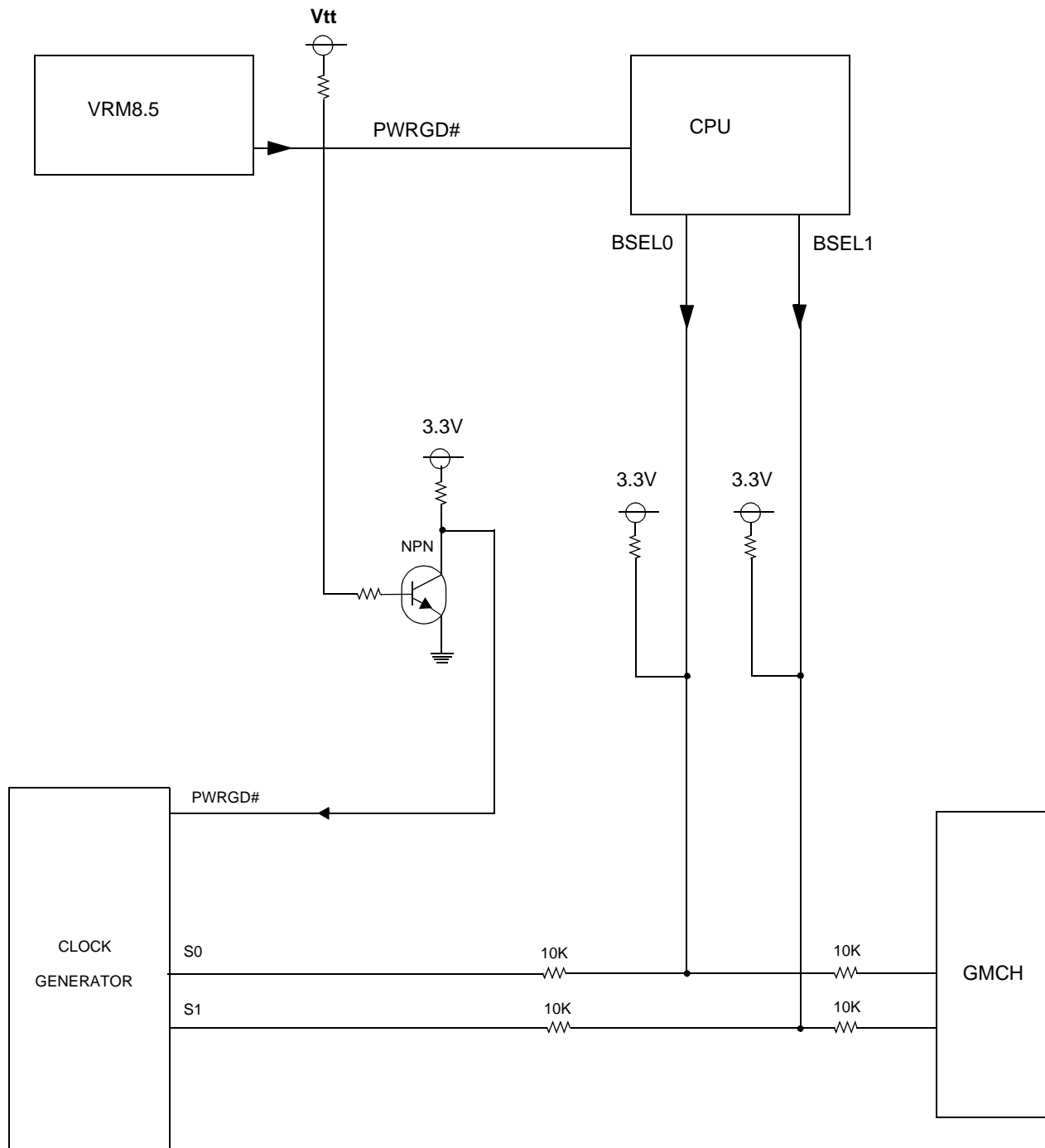
**Switching Characteristics<sup>[9]</sup> Over the Operating Range**

Parameter	Output	Description	Test Conditions	Min.	Max.	Unit
$t_1$	All	Output Duty Cycle <sup>[10]</sup>	$t_{1A}/(t_{1B})$	45	55	%
$t_2$	CPU	Rise Time	Measured at 20% to 80% of $V_{oh}$	175	700	ps
$t_2$	USB, REF, DOT	Rising Edge Rate	Between 0.4V and 2.4V	0.5	2.0	V/ns
$t_2$	PCI, 3V66,	Rising Edge Rate	Between 0.4V and 2.4V	1.0	4.0	V/ns
$t_3$	CPU	Fall Time	Measured at 80% to 20% of $V_{oh}$	175	700	ps
$t_3$	USB, REF, DOT	Falling Edge Rate	Between 2.4V and 0.4V	0.5	2.0	V/ns
$t_3$	PCI, 3V66	Falling Edge Rate	Between 2.4V and 0.4V	1.0	4.0	V/ns
$t_4$	CPU	CPU-CPU Skew	Measured at Crossover		150	ps
$t_5$	3V66 [0:1]	3V66-3V66 Skew	Measured at 1.5V		500	ps
$t_5$	66BUFF[0:2]	66BUFF-66BUFF Skew	Measured at 1.5V		175	ps
$t_6$	PCI	PCI-PCI Skew	Measured at 1.5V		500	ps
$t_7$	3V66, PCI	3V66-PCI Clock Skew	3V66 leads. Measured at 1.5V	1.5	3.5	ns
$t_8$	CPU	Cycle-Cycle Clock Jitter	Measured at Crossover $t_8 = t_{8A} - t_{8B}$ With all outputs running		200	ps
$t_9$	3V66	Cycle-Cycle Clock Jitter	Measured at 1.5V $t_9 = t_{9A} - t_{9B}$		250	ps
$t_9$	USB	Cycle-Cycle Clock Jitter	Measured at 1.5V $t_9 = t_{9A} - t_{9B}$		350	ps
$t_9$	PCI	Cycle-Cycle Clock Jitter	Measured at 1.5V $t_9 = t_{9A} - t_{9B}$		500	ps
$t_9$	REF	Cycle-Cycle Clock Jitter	Measured at 1.5V $t_9 = t_{9A} - t_{9B}$		1000	ps
	CPU, PCI	Settle Time	CPU and PCI clock stabilization from power-up		3	ms
	CPU	Rise/Fall Matching	Measured with test loads <sup>[11, 12]</sup>		20%	
	CPU	Overshoot	Measured with test loads <sup>[12]</sup>		$V_{oh} + 0.2$	V
	CPU	Undershoot	Measured with test loads <sup>[12]</sup>	-0.2		V
$V_{oh}$	CPU	High-level Output Voltage	Measured with test loads <sup>[12]</sup>	0.65	0.74	V
$V_{ol}$	CPU	Low-level Output Voltage	Measured with test loads <sup>[12]</sup>	0.0	0.05	V
$V_{crossover}$	CPU	Crossover Voltage	Measured with test loads <sup>[12]</sup>	45% of 0.65	55% of 0.74	V

**Notes:**

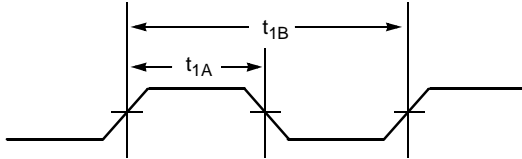
9. All parameters specified with loaded outputs.
10. Duty cycle is measured at 1.5V when  $V_{DD} = 3.3V$ . When  $V_{DD} = 2.5V$ , duty cycle is measured at 1.25V.
11. Determined as a fraction of  $2 \cdot (Trp - Trn) / (Trp + Trn)$  Where Trp is a rising edge and Trn is an intersecting falling edge.
12. The test load is  $R_s = 33.2\Omega$ ,  $R_p = 49.9\Omega$  in test circuit.



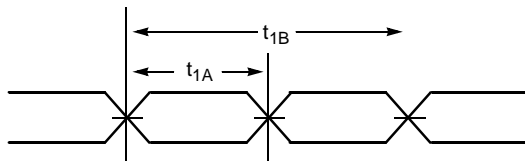
**Definition and Application of PWRGD# Signal**


## Switching Waveforms

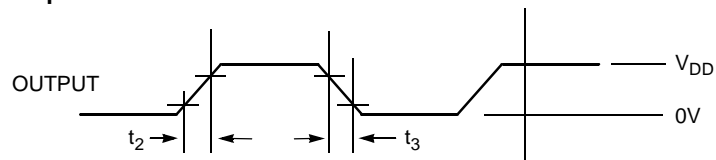
### Duty Cycle Timing (Single Ended Output)



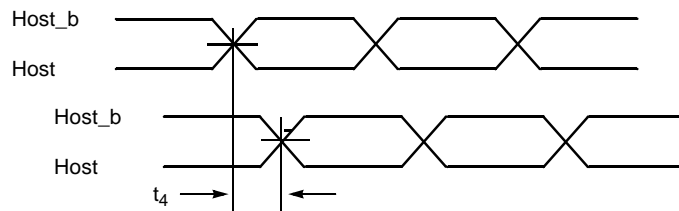
### Duty Cycle Timing (CPU Differential Output)



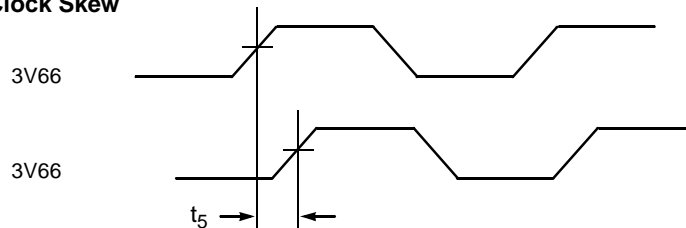
### All Outputs Rise/Fall Time

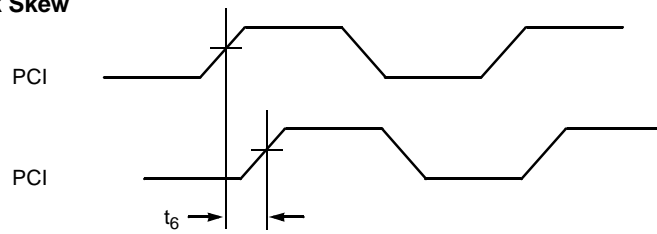
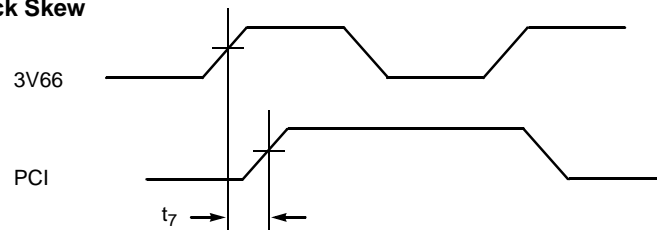
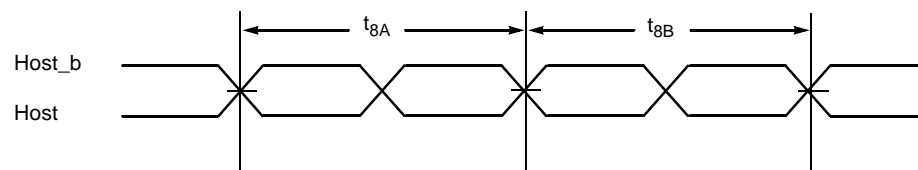
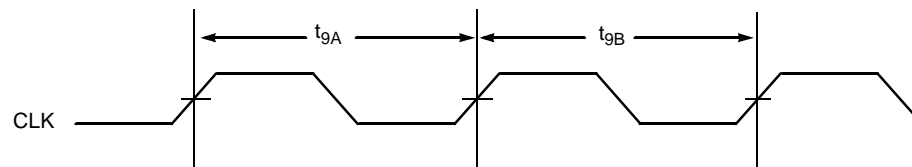


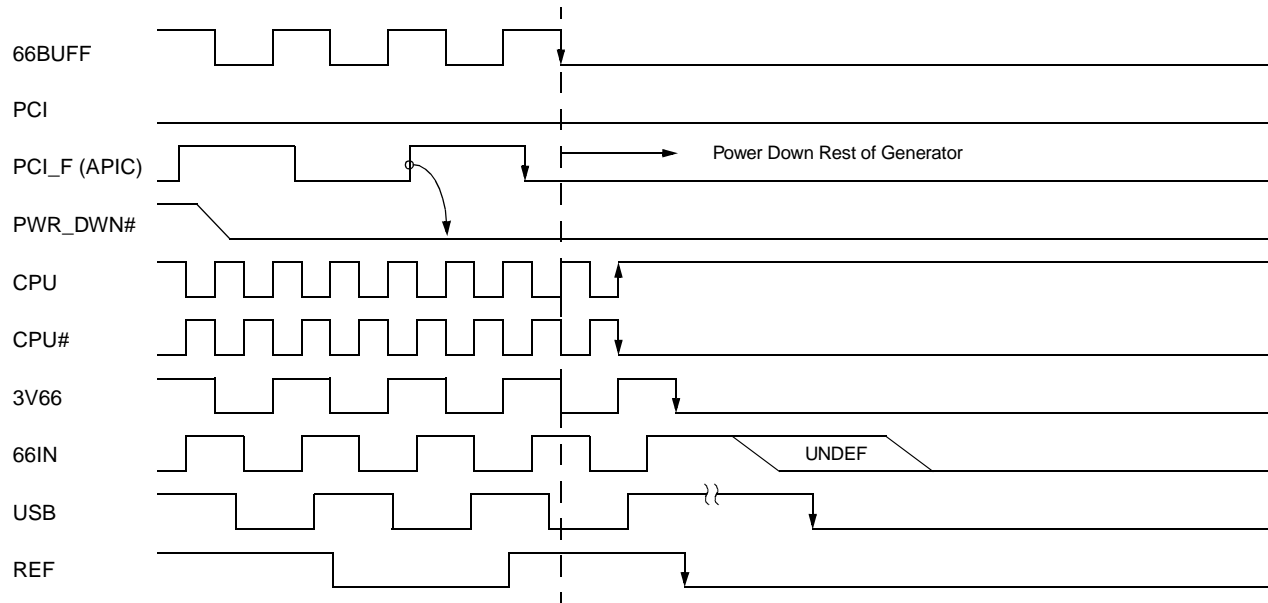
### CPU-CPU Clock Skew



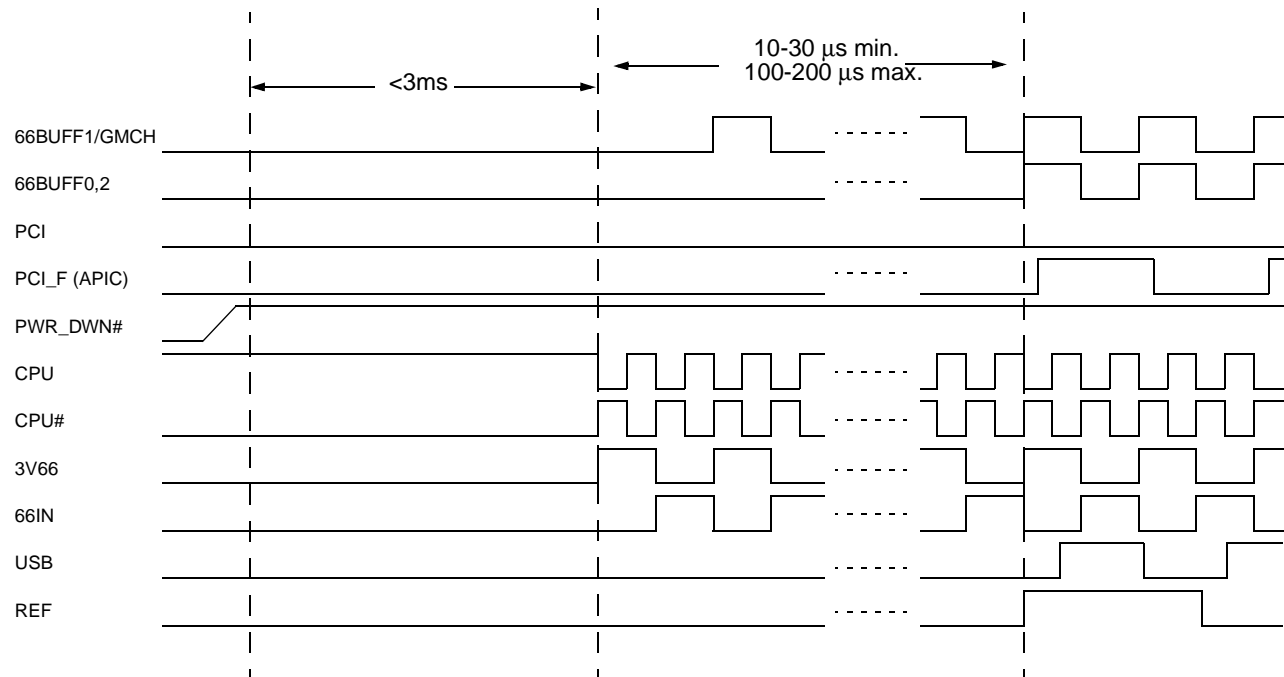
### 3V66-3V66 Clock Skew



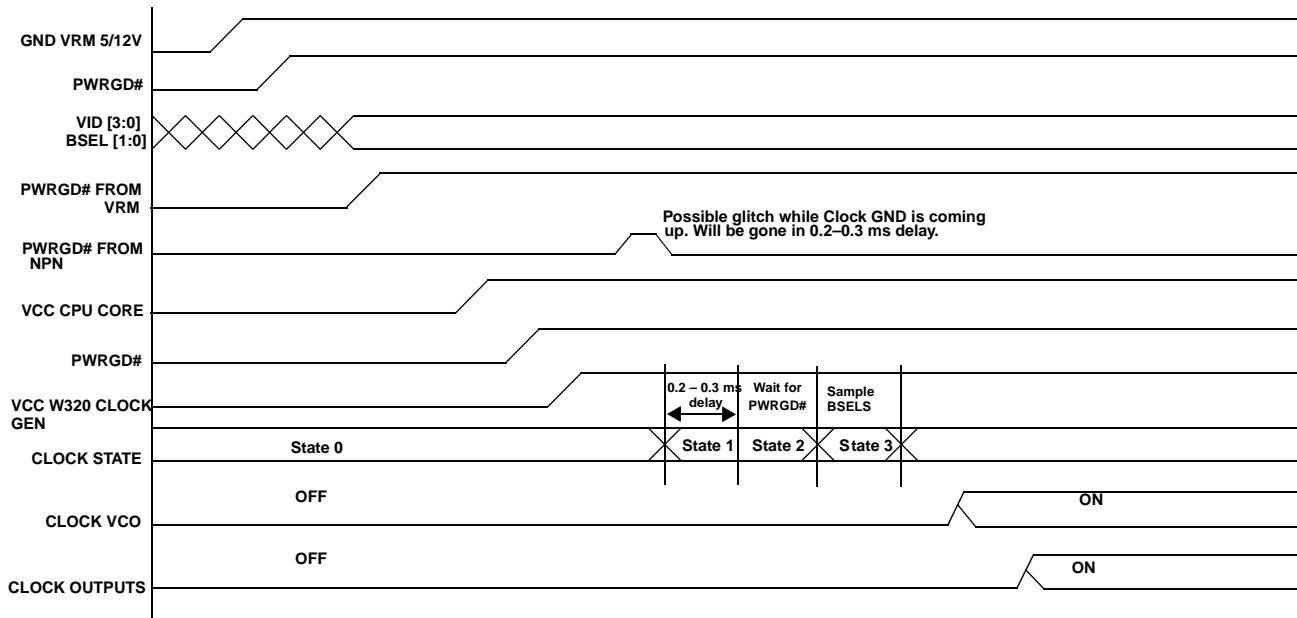
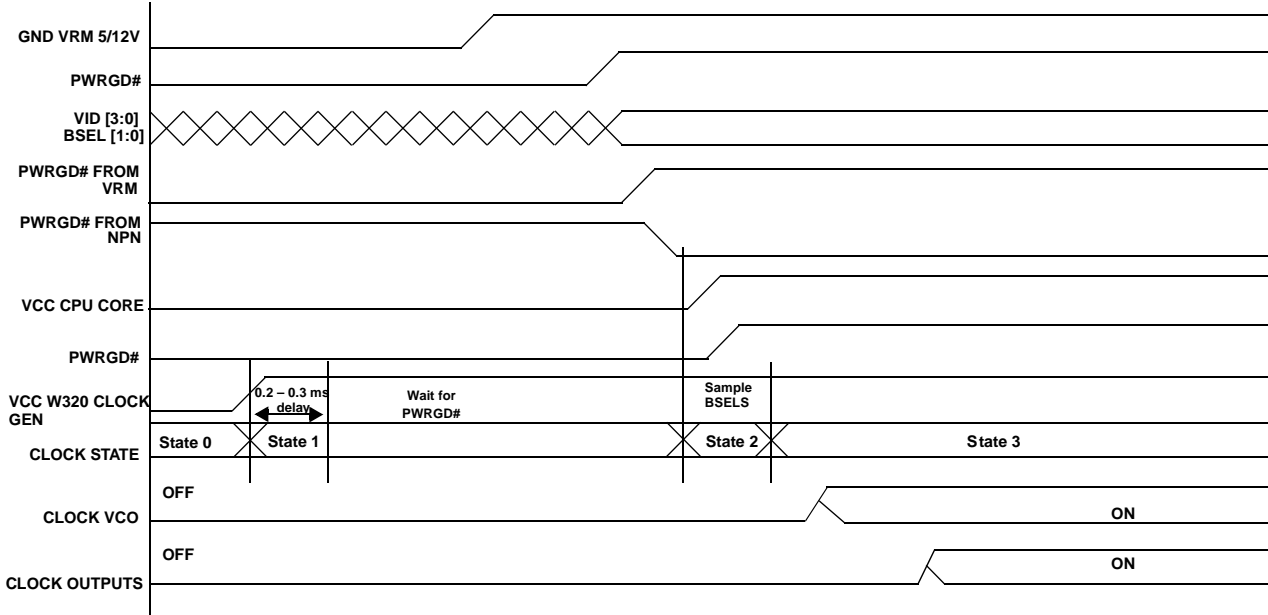
**Switching Waveforms (continued)**
**PCI-PCI Clock Skew**

**3V66-PCI Clock Skew**

**CPU Clock Cycle-Cycle Jitter**

**Cycle-Cycle Clock Jitter**


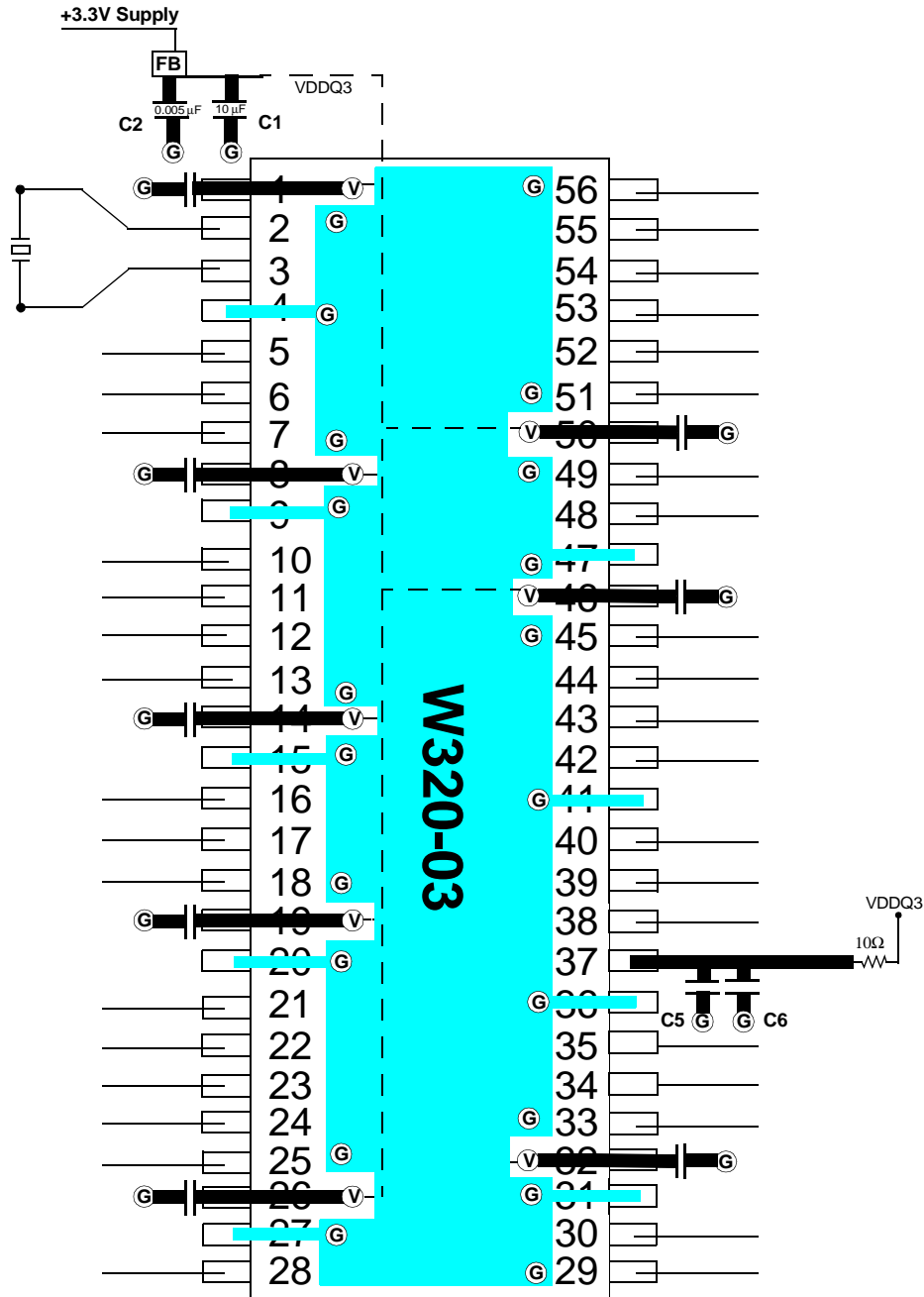
**PWRDWN# Assertion**


Note: PCI\_STOP# asserted low

**PWRDWN# De-Assertion**


Note: PCI\_STOP# asserted low

**PWRGD# Timing Diagrams**

**Figure 2. CPU Power BEFORE Clock Power**

**Figure 3. CPU Power AFTER Clock Power**

**Layout Example**


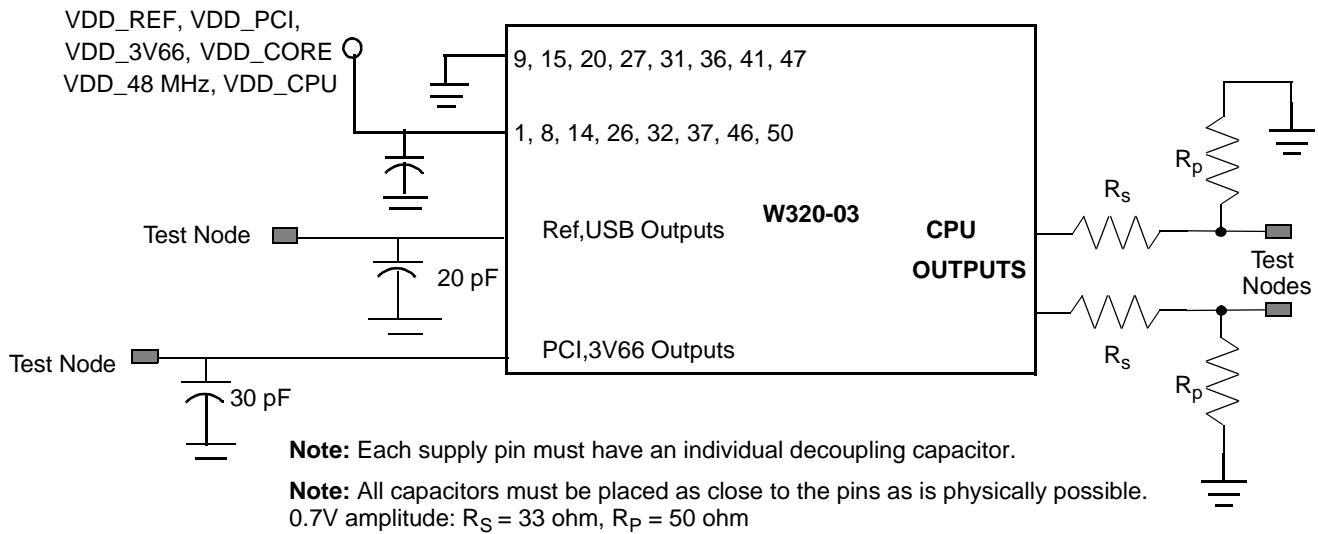
FB = Dale ILB1206 - 300 or 2TDKACB2012L-120 or 2 Murata BLM21B601S

Ceramic Caps C1 = 10–22 µF C2 = 0.005 µF C5 = 0.1 µF C6 = 10 µF

Ⓜ = VIA to GND plane layer Ⓜ = VIA to respective supply plane layer

Note: Each supply plane or strip should have a ferrite bead and capacitors

## Test Circuit



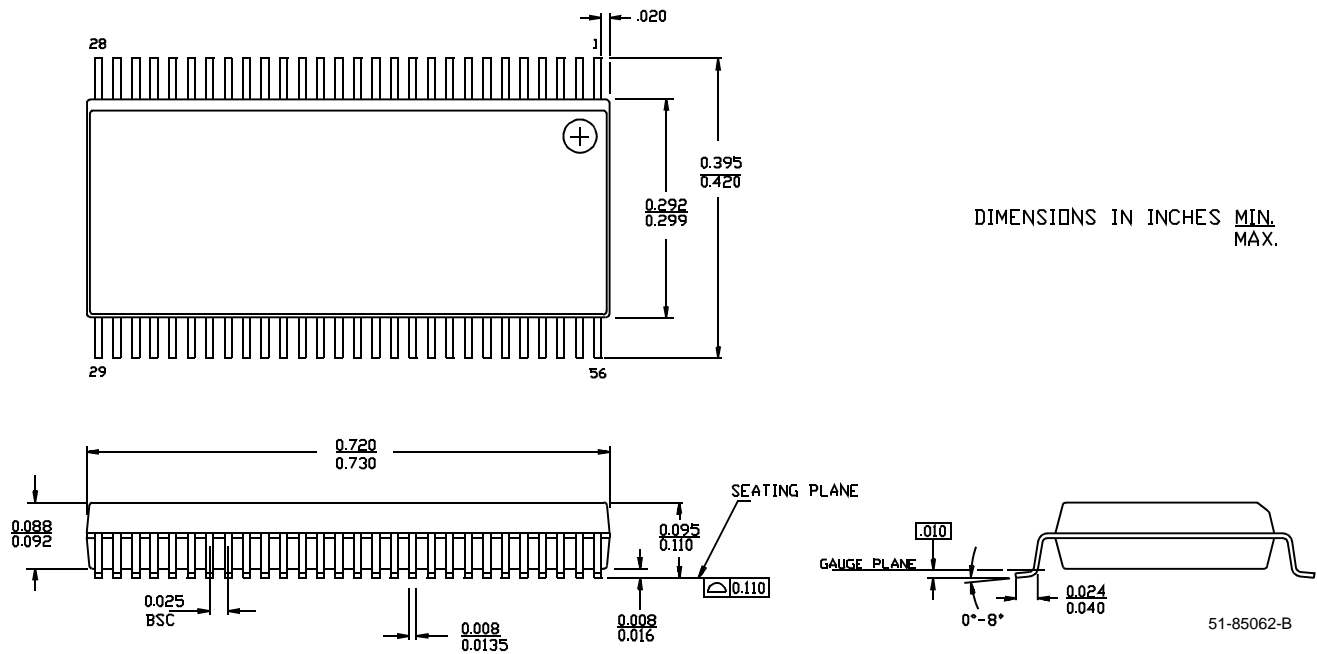
## Ordering Information

Ordering Code	Package Type	Operating Range
W320-03	H - 56-Pin SSOP X - 56-Pin TSSOP	Commercial

Document #: 38-01022-\*A

**Package Diagram**

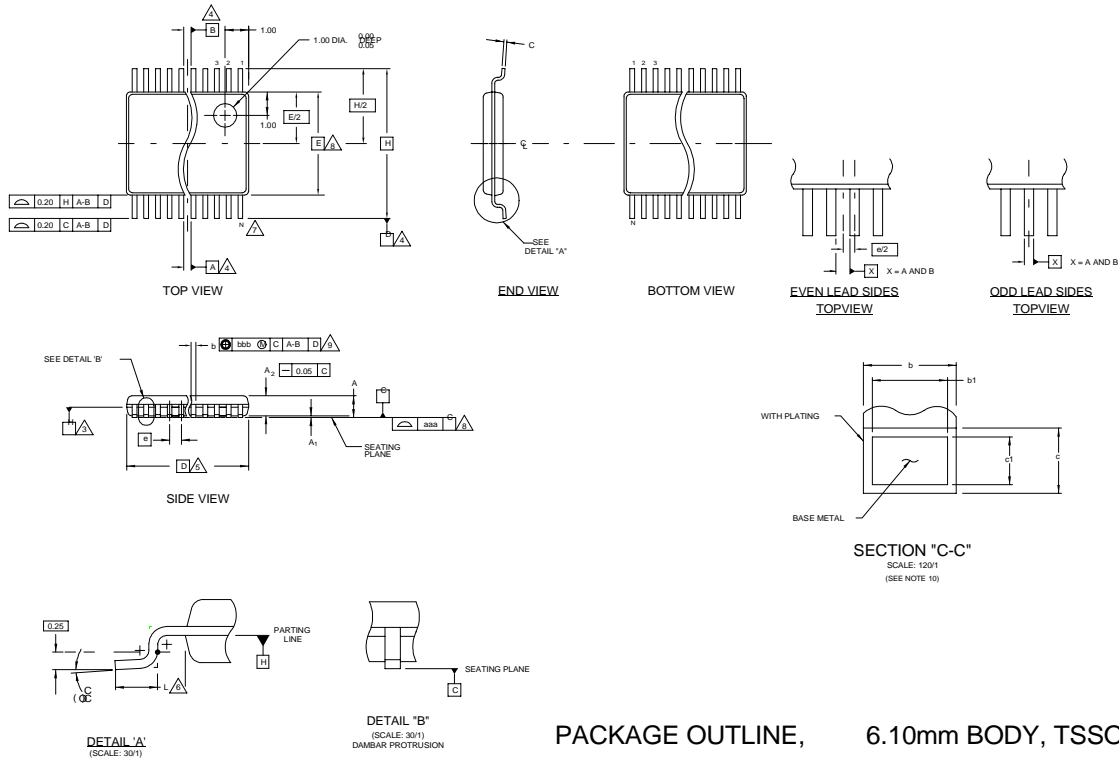
**56-Lead Shrink Small Outline Package O56**





# Package Diagram

## 56-Pin Thin Shrink Small Outline Package



PACKAGE OUTLINE, 6.10mm BODY, TSSOP

THIS TABLE FOR 0.50mm PITCH

DIM.	COMMON DIMENSIONS			NOTE	VARIATIONS			N
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.	
A	0.05	0.10	0.15	1	0.05	0.10	0.15	48
A1	0.05	0.10	0.15	1	0.05	0.10	0.15	48
A2	0.05	0.10	0.15	1	0.05	0.10	0.15	48
B	0.17	0.20	0.23	2	0.17	0.20	0.23	48
B1	0.17	0.20	0.23	2	0.17	0.20	0.23	48
C	0.05	0.10	0.15	1	0.05	0.10	0.15	48
D	0.05	0.10	0.15	1	0.05	0.10	0.15	48
E	0.05	0.10	0.15	1	0.05	0.10	0.15	48
F	0.05	0.10	0.15	1	0.05	0.10	0.15	48
G	0.05	0.10	0.15	1	0.05	0.10	0.15	48
H	0.05	0.10	0.15	1	0.05	0.10	0.15	48
I	0.05	0.10	0.15	1	0.05	0.10	0.15	48
J	0.05	0.10	0.15	1	0.05	0.10	0.15	48
K	0.05	0.10	0.15	1	0.05	0.10	0.15	48
L	0.05	0.10	0.15	1	0.05	0.10	0.15	48
M	0.05	0.10	0.15	1	0.05	0.10	0.15	48
N	0.05	0.10	0.15	1	0.05	0.10	0.15	48

ALL DIMENSIONS IN MILLIMETERS

### NOTES:

1. DIE THICKNESS ALLOWABLE IS 0.2790.0127 (.0110DIE THICKNESS ALLOWABLE IS 0.279.0005 INCHES) DIMENSIONING & TOLERANCES PER ASME. Y14.5M-1994.
2. DATUM PLANE H LOCATED AT MOLD PARTING LINE AND CONSIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
3. DATUMS A-B AND D TO BE DETERMINED WHERE CENTERLINE BETWEEN LEADS EXITS PLASTIC BODY AT DATUM PLANE H.
4. 'D' & 'E' ARE REFERENCE DATUMS AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, AND ARE MEASURED AT THE BOTTOM PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15mm ON D AND 0.25mm ON E PER SIDE.
5. DIMENSION IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
6. TERMINAL POSITIONS ARE SHOWN FOR REFERENCE ONLY.
7. FORMED LEADS SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITHIN 0.076mm AT SEATING PLANE.
8. THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND AN ADJACENT LEAD TO BE 0.10MM FOR 0.65MM PITCH, 0.08mm FOR 0.50MM PITCH AND 0.07mm FOR 0.40MM PITCH PACKAGES.
9. SEE DETAIL 'B' AND SECTION 'C-C'.
10. SECTION 'C-C' TO BE DETERMINED AT 0.10 TO 0.25 MM FROM THE LEAD TIP.
11. CONTROLLING DIMENSION: MILLIMETERS.
12. THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION MO-153, VARIATIONS DB, DC, DE, ED, EE, AND FE.